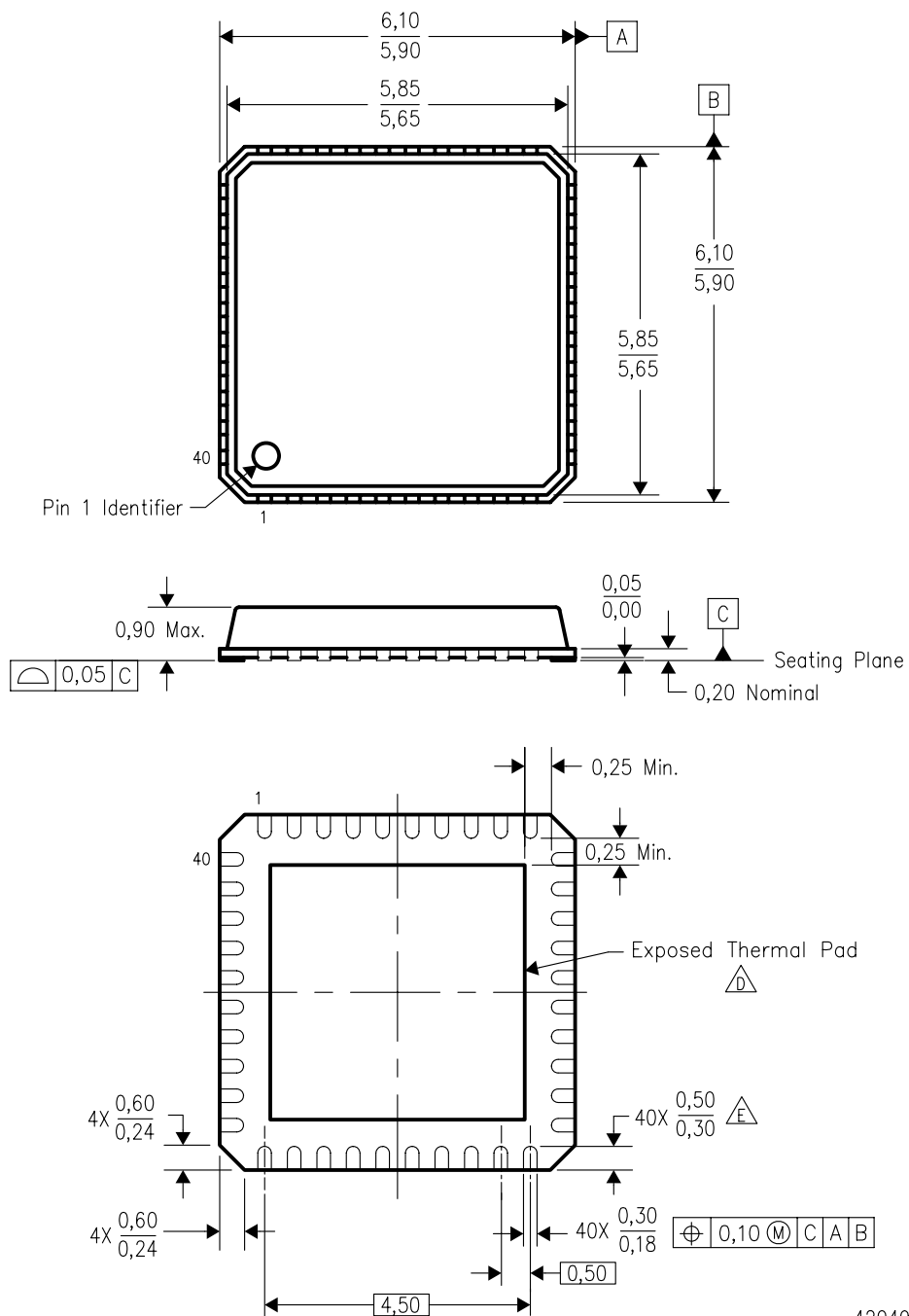


RTB (S-PQFP-N40)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters. The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
- B. This drawing is subject to change without notice. Some products have selected lands extended past 0,50 length. See Product Data Sheet for details regarding specific land length exceptions.
- C. QFN (Quad Flatpack No-Lead) Package configuration.

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